



DISCIPLINE:- ELECTRONICS & TELECOMMUNICATION ENGINEERING	SEMESTER:- 3 <sup>rd</sup>	NAME OF THE TEACHING FACULTY: SUBRAT KUMAR GRAHACHARYA	
SUBJECT TH:2- ELECTRONICS DEVICES	NO. OF DAYS/PER WEEK CLASS ALLOTTED:- 3	SEMESTER FROM DATE:- 14-07-2025	TO DATE :-15 - 11 -2025
Week	Class day	Theory	
1 <sup>st</sup>	1 <sup>st</sup>	1. Introduction to Semiconductor Physics 1.1 Review of Quantum Mechanics 1.2 Electrons in periodic Lattices	
	2 <sup>nd</sup>	1.3 Energy bands in intrinsic and extrinsic silicon	
	3 <sup>rd</sup>	1.4 Carrier transport 1.4.1 Diffusion current 1.4.2 Drift current 1.4.3 Mobility and resistivity	
2 <sup>nd</sup>	1 <sup>st</sup>	P-N Junction Diodes 2.1 Generation and recombination of carriers	
	2 <sup>nd</sup>	2.2 Poisson and continuity equatio	
	3 <sup>rd</sup>	2.3 P-N Junction Diodes 2.3.1 Construction of P-N Junction Diod	
3 <sup>rd</sup>	1 <sup>st</sup>	2.3.2 Operating Principle	
	2 <sup>nd</sup>	2.3.3 P-N junction characteristics	
	3 <sup>rd</sup>	2.3.3 P-N junction characteristics	
4 <sup>th</sup>	1 <sup>st</sup>	2.3.4 I-V characteristics	
	2 <sup>nd</sup>	2.3.5 Small signal switching model	
	3 <sup>rd</sup>	2.3.6 Avalanche breakdown	
5 <sup>th</sup>	1 <sup>st</sup>	2.3.7 Zener diod	
	2 <sup>nd</sup>	2.3.8 Schottky diode 2.3.9 LED	
	3 <sup>rd</sup>	2.3.10 Photodiode and solar cel Bipolar Junction Transistor (BJT) 3.1 Construction of BJT	
6 <sup>th</sup>	1 <sup>st</sup>	3.2 Operating Principle of BJT 3.3 Types of BJT	
	2 <sup>nd</sup>	3.4 Working principle of p-n-p and n-p-n BJT 3.5 I-V characteristics	
	3 <sup>rd</sup>	3.6 Ebers Moll Model	
7 <sup>th</sup>	1 <sup>st</sup>	3.7 Different types of transistor connection 3.7.1 Common Base (CB) 3.7.2 Common Emitter (CE) 3.7.3 Common Collector (CC)	
	2 <sup>nd</sup>	3.8 Input and output characteristics of transistor in different connections 3.9 Define ALPHA, BETA and GAMMA of transistors in various	
	3 <sup>rd</sup>	3.10 Establish the Mathematical relationship between ALPHA, BETA and GAMMA 3.11 Basic concept of Biasing	
8 <sup>th</sup>	1 <sup>st</sup>	3.12 Types of Biasing 3.13 h-parameter model of BJT	
	2 <sup>nd</sup>	3.14 Load line and determine the Q-point	
	3 <sup>rd</sup>	3.15 Types of Coupling	
9 <sup>th</sup>	1 <sup>st</sup>	3.16 Working principle and use of R-C Coupled Amplifier	

	2 <sup>nd</sup>	<b>3.17 Frequency Responses of R-C coupled Amplifier</b>
	3 <sup>rd</sup>	<b>FIELD EFFECT TRANSISTOR (FET)</b> <b>4.1 FET &amp; its classifications</b>
10 <sup>th</sup>	1st	<b>4.2 Differentiate between JFET &amp; BJT</b>
	2 <sup>nd</sup>	<b>4.3 Construction, working principle &amp; characteristics of JEFT</b>
	3 <sup>rd</sup>	<b>4.4 Parameters of JFET &amp; establish relation among JFET parameters</b>
11 <sup>th</sup>	1st	<b>4.5 Construction and working principle of MOSEFT</b>
	2 <sup>nd</sup>	<b>4.6 Classification of MOSEFT</b>
	3 <sup>rd</sup>	<b>4.7 Characteristics (Drain &amp; Transfer) of MOSEF</b>
12 <sup>th</sup>	1st	<b>4.8 Explain the operation of CMOS, VMOS &amp; LDMOS.</b>
	2 <sup>nd</sup>	<b>FEED BACK AMPLIFIER &amp; OSCILLATOR</b> <b>5.1 Define &amp; classify Feedback Amplifier</b>
	3 <sup>rd</sup>	<b>5.2 Types of feedback – negative &amp; positive feedback.</b>
13 <sup>th</sup>	1st	<b>5.3 Characteristics voltage gain, bandwidth, input Impedance output impedance, stability, noise and distortion in amplifiers.</b>
	2 <sup>nd</sup>	<b>5.4 Oscillator</b> <b>5.4.1 Block diagram of sine wave oscillator</b> <b>5.4.2 Types Requirement of oscillation</b> <b>5.4.3 Barkhausen criterion</b>
	3 <sup>rd</sup>	<b>5.4 Oscillator</b> <b>5.4.1 Block diagram of sine wave oscillator</b> <b>5.4.2 Types Requirement of oscillation</b> <b>5.4.3 Barkhausen criterion</b>
14 <sup>th</sup>	1st	<b>5.5 LC oscillators</b> <b>5.5.1 Colpitts Oscillators</b>
	2 <sup>nd</sup>	<b>5.5.2 Hartley Oscillators</b> <b>5.5.3 Wien Bridge Oscillators</b>
	3 <sup>rd</sup>	<b>Integrated Circuit Fabrication Process</b> <b>6.1 Oxidation</b> <b>6.2 Diffusion</b>
15 <sup>th</sup>	1st	<b>6.3 Ion implantation</b> <b>6.4 Photo-lithography</b>
	2 <sup>nd</sup>	<b>6.5 Etching</b> <b>6.6 Chemical vapor deposition</b>
	3 <sup>rd</sup>	<b>6.7 Sputtering</b> <b>6.8 Twin-tub CMOS process</b>

*S.K.O  
11/10/25*  
Signature of faculty

*Deek  
11/10/25*  
Signature of sr lecturer  
**Head of Dept. (HOD)  
Electrical & ETC Engg.  
G.I.E.T (POLY), ...**

*11/10/25*  
Signature of principal